



## Material Content Data Sheet



<b>Sales Product Name</b>		ILD1150		<b>Issued</b>		4. July 2019		
<b>MA#</b>		MA005344651						
<b>Package</b>		PG-SSOP-14-3		<b>Weight*</b>		83.07 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.030	2.44	2.44	24437	24437
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		104	
	non noble metal	zinc	7440-66-6	0.034	0.04		415	
	non noble metal	iron	7439-89-6	0.689	0.83		8295	
wire	non noble metal	copper	7440-50-8	27.978	33.68	34.56	336808	345622
	noble metal	gold	7440-57-5	0.209	0.25	0.25	2514	2514
	encapsulation	organic material	carbon black	1333-86-4	0.099	0.12		1196
plastics		epoxy resin	-	4.570	5.50		55010	
	inorganic material	silicondioxide	60676-86-0	45.000	54.18	59.80	541729	597935
leadfinish	non noble metal	tin	7440-31-5	0.976	1.18	1.18	11751	11751
plating	noble metal	silver	7440-22-4	0.768	0.92	0.92	9241	9241
glue	plastics	epoxy resin	-	0.177	0.21		2125	
	noble metal	silver	7440-22-4	0.530	0.64	0.85	6375	8500
*deviation	< 10%					Sum in total:	100.00	1000000

### Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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